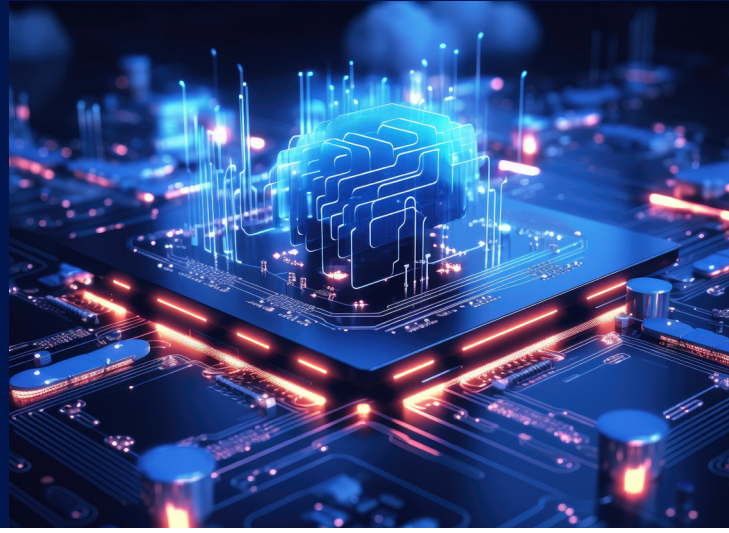


# High-Performance Edge Computing for Intelligent Industries



## ABOX-5221

### Fanless Edge AI with ThermoSiphon™ Cooling



The expansion of Edge AI creates a critical thermal challenge: high-performance components generate massive heat that overwhelms traditional fans and pumps, leading to system failure from dust and mechanical wear. The [ABOX-5221](#) solves this with patented ThermoSiphon™ technology, a pump-less, self-circulating liquid cooling loop that requires zero energy. This breakthrough enables a fully sealed, maintenance-free chassis capable of unthrottled operation from -40°C to 70°C. Unlike conventional solutions, it eliminates all moving parts and integrates a Backup Battery Unit (BBU) to prevent data loss. With support for 14th Gen Intel® Core™ processor, plus dual 10GbE, it redefines reliability for mission-critical applications.



### Key Features



Pump-less  
Liquid Cooling



High-Performance  
Computing Power



10-Min Backup  
Battery



Dual 10GbE  
Connectivity

### Intel Products & Technology



Intel® Core™  
Processors



OpenVINO™  
Toolkit

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